CLAIMS

1. A positive photosensitive composition comprising:

(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group,

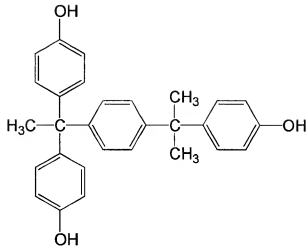
(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat,

(C) at least one resin selected from the group consisting of; (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethylaminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin, and

(D) a dissolution inhibitor.

2. The positive photosensitive composition according to claim 1, wherein the dissolution inhibitor (D) is a compound represented by the following chemical formula (1).

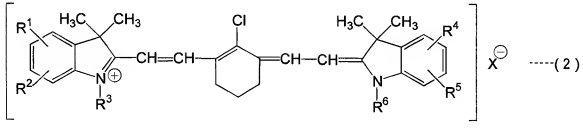
[Chemical formula 21]



-----(1)

3. The positive photosensitive composition according to claim 1 or 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).

[Chemical formula 22]

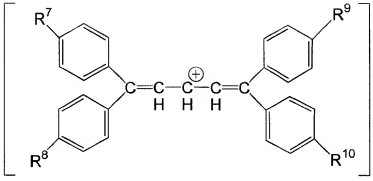


-----(2)

wherein each of "R1" to "R6" independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxyl group having 1 to 3 carbon atoms, and "X" represents a halogen atom, ClO_4, BF_4, $p\text{-}CH_3C_6H_4SO_3$, or PF_6.

4. The positive photosensitive composition according to claim 1 or 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (3).

[Chemical formula 23]



-----(3)

wherein each of "R^7"~"R^{10}" independently represents a hydrogen atom, a methoxyl group, $N(CH_3)_2$, or $N(C_2H_5)_2$, and "Y" represents C_4H_9-$B(C_6H_5)_3$, p-$CH_3C_6H_4SO_3$, or CF_3SO_3.

5. A photofabrication method using the positive photosensitive composition according to any of claims 1 to 4.

6. The photofabrication method according to claim 5, which is applied to production of a printing plate, an electronic component and a precision equipment component.

7. A plate-making method using the positive photosensitive composition according to any of claims 1 to 4.